IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Thibaut MAURICE et al. Confirmation No.: To Be Assigned Application No.: To Be Assigned Group Art Unit: To Be Assigned Filing Date: Herewith Examiner: To Be Assigned For: PREPARATION METHOD FOR Attorney Docket No.: 4717-12000 PROTECTING THE BACK SURFACE OF A WAFER AND BACK SURFACE PROTECTED WAFER POWER OF ATTORNEY BY ASSIGNEE AND EXCLUSION OF INVENTOR(S) UNDER 37 C.F.R. 3.71 Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450 Sir: The undersigned assignee of the entire interest in the above-identified subject application hereby appoints Allan A. Fanucci (Reg. No. 30,256) and Daniel J. Hulseberg (Reg. No. 36,554) of WINSTON & STRAWN LLP (Customer No. 28765) to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith. Please direct all correspondence for this application to Customer No. 28765 to the attention of Allan A. Fanucci (telephone 212-294-3311, facsimile 212-294-4700). An assignment of the entire interest in the above-identified subject application: is submitted herewith for recording and a copy is attached. was submitted for recordation on _____ and a copy is attached. was recorded on ______ at Reel _____, Frame _____. The undersigned has reviewed this assignment and, to the best of his/her knowledge, title is in the assignee seeking to take action in this application and that he/she is empowered to act on its behalf. **ASSIGNEE:** S.O.I. TEC SILICON ON INSULATOR TECHNOLOGIES S.A. Signature: Date of Signature: Typed Name:

IP MANAGER

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Position/Title:

DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled in:

PREPARATION METHOD FOR PROTECTING THE BACK SURFACE OF A WAFER AND BACK SURFACE PROTECTED WAFER

and for which a patent applicati	ion: des amendment(s) filed on			(iı	f applicable)
was filed in the United State	(declaration not accompanying application) with				
amendment(s) filed on	nal Application No	(if applicable)	•		
was filed as PCT internation	ıal Application No	on			and was amended
under PCT Article 19 on		(if applicable)			
I hereby state that I have revi amended by any amendment ref	iewed and understand the conter ferred to above.	nts of the above iden	tified applic	ation, inclu	iding the claims, as
I acknowledge the duty to discle Regulations, § 1.56.	ose information known to me to b	be material to patentab	ility as defir	ned in Title	37, Code of Federal
inventor's certificate listed belo	benefits under Title 35, United Stow and have also identified below pplication on which priority is cla	any foreign application			
EARLIEST FOREIGN AP	PPLICATION(S), IF ANY, FILEI	D PRIOR TO THE FIL	LING DATE	OF THE A	APPLICATION
APPLICATION NUMBER	COUNTRY	DATE OF FIL (day, month, y		PRIORITY CLAIMED	
03291253.7	Europe	May 26, 20	03	⊠ YES	□ NO
				☐ YES	□ NO
I hereby claim the benefit und below.	der Title 35, United States Code,	, § 119(e) of any Uni	ted States p	provisional	application(s) listed
PROVISIONAL APPLICATION NUMBER		FILING DATE			
as the subject matter of each of provided by the first paragraph me which is material to patental	er Title 35, United States Code, § the claims of this application is 1 of Title 35, United States Code bility as defined in Title 37, Code cation and the national or PCT int	not disclosed in the pr § 112, I acknowledge e of Federal Regulatio	ior United S the duty to ns, § 1.56 w	States applic disclose in which became cation:	cation in the manner formation known to
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^{*} for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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